ON Semiconductor

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16913

Generic Copy

Issue Date: 05-Oct-2012

TITLE: Final notification for conversion of heat seal cover tape to 3M UCT cold seal cover tape for wafer scale packaging (WSP) bare die products.

PROPOSED FIRST SHIP DATE: 05-Jan-2013

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Assembly Site

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor sales office or Vincent Tan Hock Seong
<vincent.tan@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor sales office or Vincent Tan Hock Seong
<vincent.tan@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

To support ON Semiconductor's Continuous Improvement efforts, ON Semiconductor will be converting the Tape and Reel Cover Tape of our wafer scale packaging (WSP) bare die products from HAA Cover Tape (Heat Activated Adhesive) to UCT Cold Seal Cover Tape (Universal Cover Tape)

This will eliminated potential process inherent issue (torn tape, unsealing & stringing) due to heat seal process and provide a consistence peel force with small standard deviation.

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RELIABILITY DATA SUMMARY:

Reliability Test Results:

Test	**Conditions**	**Results**
MSL 1	85 degree C, 85% humidity	No bond pad contamination after 168hours No die stick on cover tape after 4 hours.

ELECTRICAL CHARACTERISTIC SUMMARY:

No change.

CHANGED PART IDENTIFICATION:

There will be no changes. Normal assembly lot traceability codes will identify.

List of affected General Parts:

20775-001-XDS